

the first laser beam, and forming a film vaporized from said marking material onto a predetermined area of said material to be marked; and

a second process of removing a part of said film formed onto the surface of said material to be marked by irradiating the part of the film with a second laser beam while scanning with the second laser beam;

wherein patterns of characters, diagrams or symbols are formed on said material to be marked; and

wherein said desired gap is between $2\mu\text{m}$ and $200\mu\text{m}$.

10. (Four Times Amended) A method for marking materials according to claim 1,

wherein the deposited marking material is a thin film formed on the surface of the material to be marked having a thickness from $0.1\mu\text{m}$ to $2\mu\text{m}$.
